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February 25, 2002

Commissioner of Patents and Trademarks
Box Patent Application
Washington, D.C. 20231

Re: SENSOR STRUCTURES AND METHODS FOR REDUCTION OF
DIFFERENTIAL-HEATING SIGNAL ERRORS IN INTEGRATED
CIRCUITS
Docket No. A5WI2038US

Sir:

Transmitted herewith for filing under 35 U.S.C. 111 and 37
CFR 1.53 is the patent application of STEPHEN A. COHEN entitled
SENSOR STRUCTURES AND METHODS FOR REDUCTION OF DIFFERENTIAL-HEAT-
ING SIGNAL ERRORS IN INTEGRATED CIRCUITS.

Enclosed are:

19 pages of written description, claims and abstract.
7 sheets of drawings.
An Assignment of the invention to ANALOG DEVICES, INC. ✓
Executed Declaration and Power of Attorney of the inventors.
Information Disclosure Statement, Form PTO-1449, references.
Request for Non-Publication.

The filing and recording fees have been calculated as shown
below:

Basic Fee		\$740.00
Total Claims	(34 - 20) x \$18.00 =	252.00
Independent Claims	(4 - 3) x \$84.00 =	84.00
Assignment Recording Fee		<u>40.00</u>
Total Fee:		\$1,116.00

Our Check No. 17842 for \$1,116.00 to cover the filing and
recording fees is enclosed. We authorize the Commissioner to
charge (1) payment of any additional filing fees required under
37 CFR §1.16, (2) payment of any patent application processing
fees under 37 CFR §1.17 associated with this communication, or
(3) payment of any fees that occur during the pendency of this
application (and to credit any overpayment) to Deposit Account
No. 11-1580. We enclose a duplicate copy of this sheet.

Very truly yours,
KOPPEL, JACOBS, PATRICK & HEYBL

Richard S. Koppel
Richard S. Koppel
Registration No. 26,475

RSK/jc
Enclosures
J\D2\A2038 Patent Trs

jc997 U.S. PTO
10/083752

02/25/02

**REQUEST AND CERTIFICATION
UNDER
35 U.S.C. 122(b)(2)(B)(i)**

First Named Inventor

STEPHEN A. CHOEN

Title

SENSOR STRUCTURES AND METHODS FOR REDUCTION
OF DIFFERENTIAL-HEATING SIGNAL ERRORS IN
INTEGRATED CIRCUITS

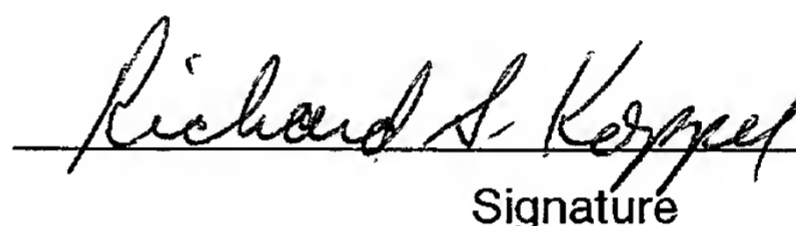
Atty Docket Number

A5WI2038US

I hereby certify that the invention disclosed in the attached application **has not and will not be** the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

February 25, 2002

Date



Signature

Richard S. Koppel

Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**